



- NOTES:
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE :
 W/B NO.15,16,45,46,75,76,105,106 ----- 200mOHMS MAX.
 W/B NO.1,31,61,91 ----- 500mOHMS MAX.
 THE OTHERS ----- 800mOHMS MAX.

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						120 PIN GRID ARRAY PACKAGE	UNLESS OTHERWISE SPECIFIED	S.N	T.A		FEB 15 '85
	△ REDRAWN	APR 16 '81	N.I	A.F/T.A	M.K	SCALE 5/1	MATERIAL AS INDICATED				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.			SHEET
								KD-P85083-A			1/3

PB120R083-1 5-0

WIRE BOND PAD / CONNECTOR PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.
1	C3	27	M1	53	N10	79	F12	105	B7
2	B2	28	K3	54	L9	80	F11	106	C7
3	B1	29	L2	55	M10	81	E13	107	A7
4	D3	30	N1	56	N11	82	E12	108	A6
5	C2	31	L3	57	N12	83	D13	109	B6
6	C1	32	M2	58	L10	84	E11	110	C6
7	D2	33	N2	59	M11	85	D12	111	A5
8	E3	34	L4	60	N13	86	C13	112	B5
9	D1	35	M3	61	L11	87	B13	113	A4
10	E2	36	N3	62	M12	88	D11	114	C5
11	E1	37	M4	63	M13	89	C12	115	B4
12	F3	38	L5	64	K11	90	A13	116	A3
13	F2	39	N4	65	L12	91	C11	117	A2
14	F1	40	M5	66	L13	92	B12	118	C4
15	G2	41	N5	67	K12	93	A12	119	B3
16	G3	42	L6	68	J11	94	C10	120	A1
17	G1	43	M6	69	K13	95	B11		
18	H1	44	N6	70	J12	96	A11	S/R	NC
19	H2	45	M7	71	J13	97	B10	D/A	NC
20	H3	46	L7	72	H11	98	C9	EXTRA PIN	NC
21	J1	47	N7	73	H12	99	A10	D4	
22	J2	48	N8	74	H13	100	B9		
23	K1	49	M8	75	G12	101	A9		
24	J3	50	L8	76	G11	102	C8		
25	K2	51	N9	77	G13	103	B8		
26	L1	52	M9	78	F13	104	A8		

S/R	NC
D/A	NC
EXTRA PIN	NC
D4	

MODIFICATION					NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE	
					120 PIN GRID ARRAY PACKAGE	UNLESS OTHERWISE SPECIFIED	S.N	T.A		FEB.15.'05	
	△ REDRAWN	APR.15.04	N.I	A.F/T.A	M.K	SCALE	/				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	MATERIAL					
							KYOCERA CORPORATION KYOTO JAPAN		DRAWING NO. KD-P85083-A		SHEET 3/3